

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages V_{DRM} and V_{RRM} V	Conditions
DCR3030V42	4200	$T_{vj} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$, $I_{DRM} = I_{RRM} = 200\text{mA}$, $V_{DRM}, V_{RRM} t_p = 10\text{ms}$, $V_{DSM} \text{ \& } V_{RSM} =$ $V_{DRM} \text{ \& } V_{RRM} + 100\text{V}$ respectively
DCR3030V40	4000	
DCR3030V35	3500	
DCR3030V30	3000	

Lower voltage grades available.

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR3030V42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS

V_{DRM}	4200V
$I_{T(AV)}$	3030A
I_{TSM}	40600A
dV/dt^*	1500V/ μs
dI/dt	400A/ μs

* Higher dV/dt selections available

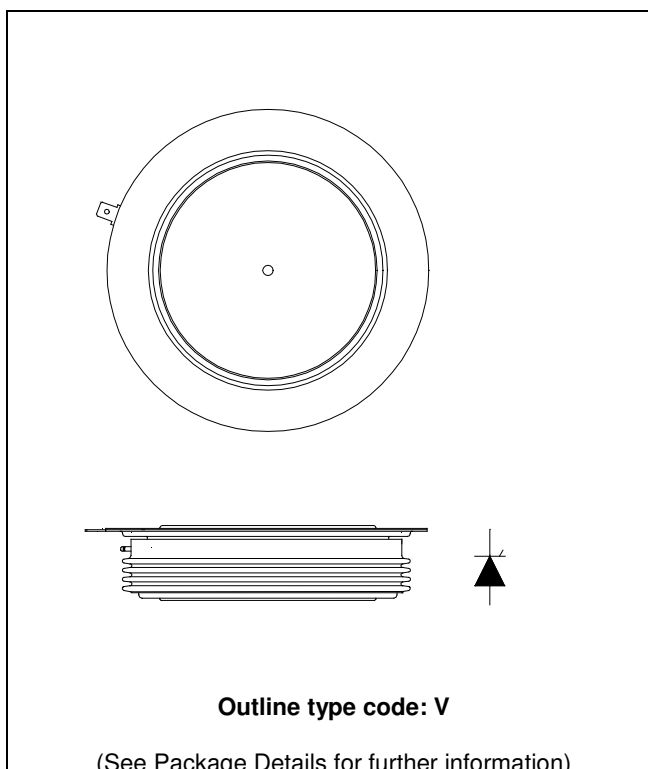


Fig. 1 Package outline

CURRENT RATINGS

$T_{case} = 60^{\circ}\text{C}$ unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Side Cooled				
$I_{T(AV)}$	Mean on-state current	Half wave resistive load	3030	A
$I_{T(RMS)}$	RMS value	-	4760	A
I_T	Continuous (direct) on-state current	-	4550	A

SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
I_{TSM}	Surge (non-repetitive) on-state current	10ms half sine, $T_{case} = 125^{\circ}\text{C}$	40.6	kA
I^2t	I^2t for fusing	$V_R = 0$	8.24	MA^2s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance – junction to case	Double side cooled	DC	-	0.00746	$^{\circ}\text{C/W}$
		Single side cooled	Anode DC	-	0.0130	$^{\circ}\text{C/W}$
			Cathode DC	-	0.0178	$^{\circ}\text{C/W}$
$R_{th(c-h)}$	Thermal resistance – case to heatsink	Clamping force 54kN (with mounting compound)	Double side	-	0.002	$^{\circ}\text{C/W}$
			Single side	-	0.004	$^{\circ}\text{C/W}$
T_{vj}	Virtual junction temperature	On-state (conducting)		-	135	$^{\circ}\text{C}$
		Reverse (blocking)		-	125	$^{\circ}\text{C}$
T_{stg}	Storage temperature range			-55	125	$^{\circ}\text{C}$
F_m	Clamping force			48.0	59.0	kN

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Conditions		Min.	Max.	Units
I _{RRM} /I _{DRM}	Peak reverse and off-state current	At V _{RRM} /V _{DRM} , T _{case} = 125 °C		-	200	mA
dV/dt	Max. linear rate of rise of off-state voltage	To 67% V _{DRM} , T _j = 125 °C, gate open		-	1500	V/μs
dI/dt	Rate of rise of on-state current	From 67% V _{DRM} to 2x I _{T(AV)}	Repetitive 50Hz	-	200	A/μs
		Gate source 30V, 10Ω, t _r < 0.5μs, T _j = 125 °C	Non-repetitive	-	400	A/μs
V _{T(TO)}	Threshold voltage – Low level	200A to 1700A at T _{case} = 125 °C		-	0.82	V
	Threshold voltage – High level	1700A to 7000A at T _{case} = 125 °C		-	0.98	V
r _T	On-state slope resistance – Low level	200A to 1700A at T _{case} = 125 °C		-	0.292	mΩ
	On-state slope resistance – High level	1700A to 7000A at T _{case} = 125 °C		-	0.198	mΩ
t _{gd}	Delay time	V _D = 67% V _{DRM} , gate source 30V, 10Ω t _r = 0.5μs, T _j = 25 °C		TBD	TBD	μs
t _q	Turn-off time	T _j = 125 °C, V _R = 200V, dI/dt = 1A/μs, dV _{DR} /dt = 20V/μs linear		250	500	μs
Q _S	Stored charge	T _j = 125 °C, dI/dt – 1A/μs, V _{R pk} =3000V, V _{RM} = 1700V		1600	3500	μC
I _L	Latching current	T _j = 25 °C, V _D = 5V		-	3	A
I _H	Holding current	T _j = 25 °C, R _{G-K} = ∞, I _{TM} = 500A, I _T = 5A		-	300	mA

GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
V_{GT}	Gate trigger voltage	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	1.5	V
V_{GD}	Gate non-trigger voltage	At $V_{DRM}, T_{case} = 125^{\circ}C$	TBD	V
I_{GT}	Gate trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	250	mA
I_{GD}	Gate non-trigger current	$V_{DRM} = 5V, T_{case} = 25^{\circ}C$	TBD	mA

CURVES

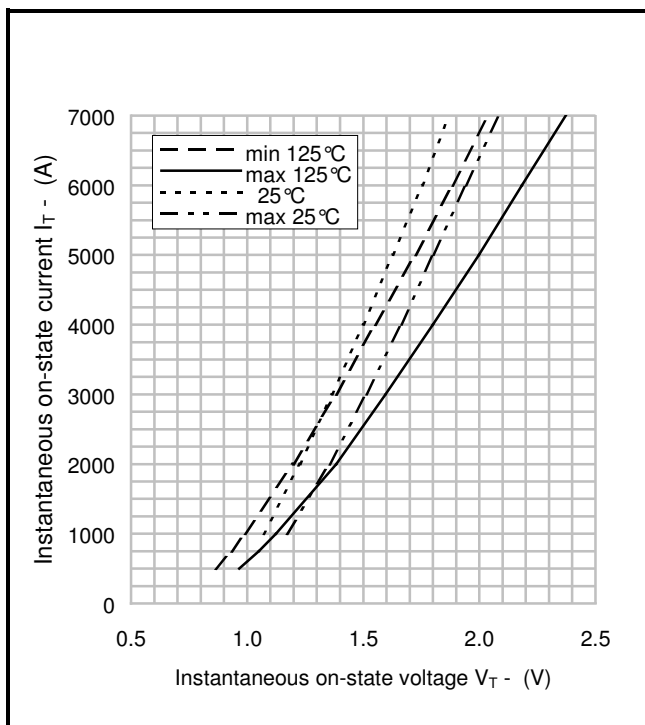


Fig.2 Maximum & minimum on-state characteristics

V_{TM} EQUATION

$$V_{TM} = A + B \ln(I_T) + C \cdot I_T + D \cdot \sqrt{I_T}$$

Where $A = 0.866995$
 $B = -0.042053$
 $C = 0.000100$
 $D = 0.014062$

these values are valid for $T_j = 125^{\circ}C$ for I_T 500A to 10000A

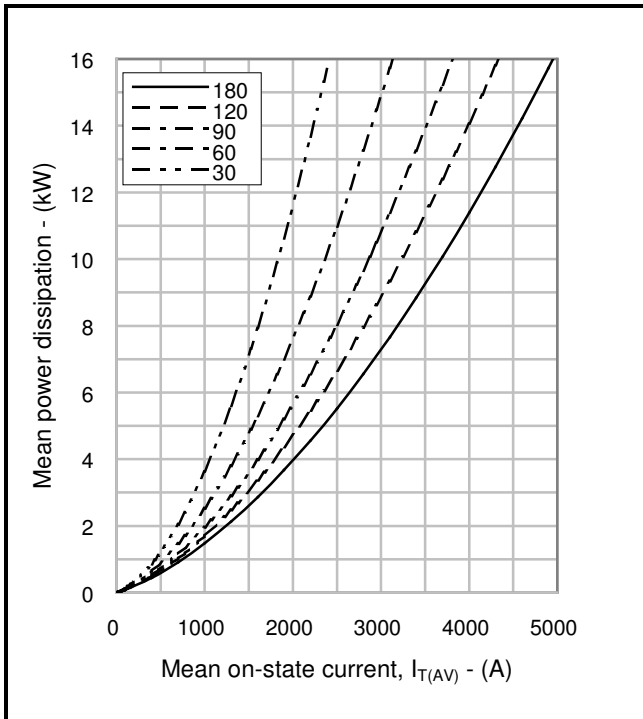


Fig.3 On-state power dissipation – sine wave

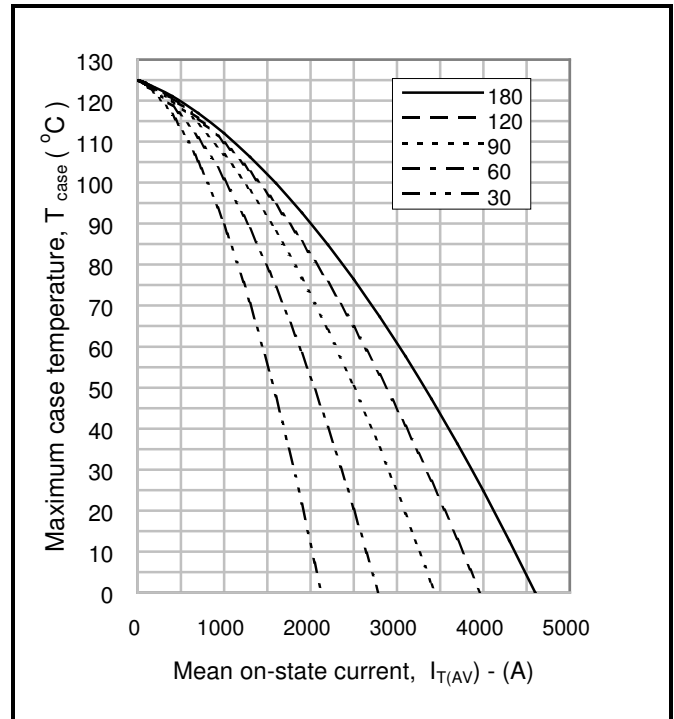


Fig.4 Maximum permissible case temperature, double side cooled – sine wave

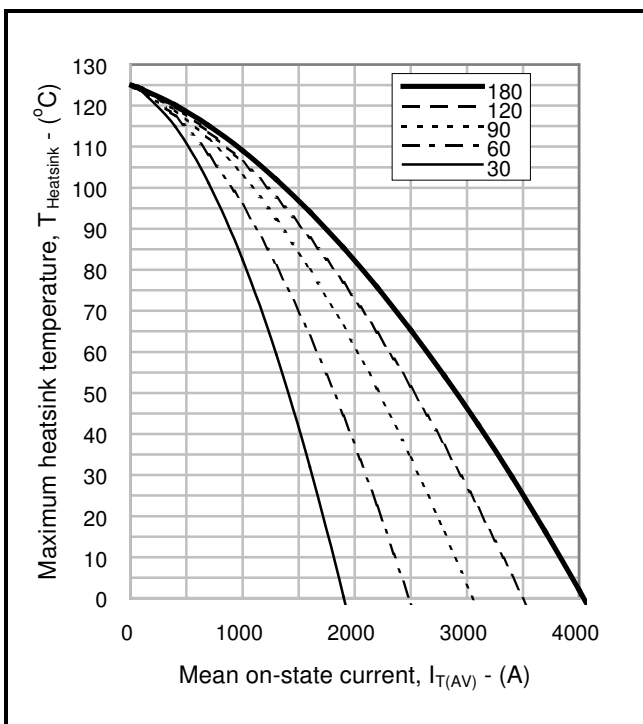


Fig.5 Maximum permissible heatsink temperature, double side cooled – sine wave

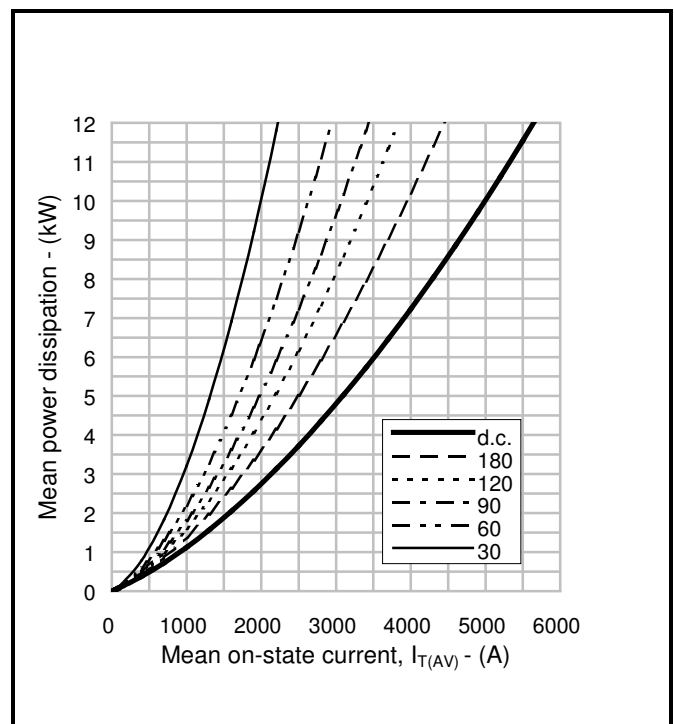


Fig.6 On-state power dissipation – rectangular wave

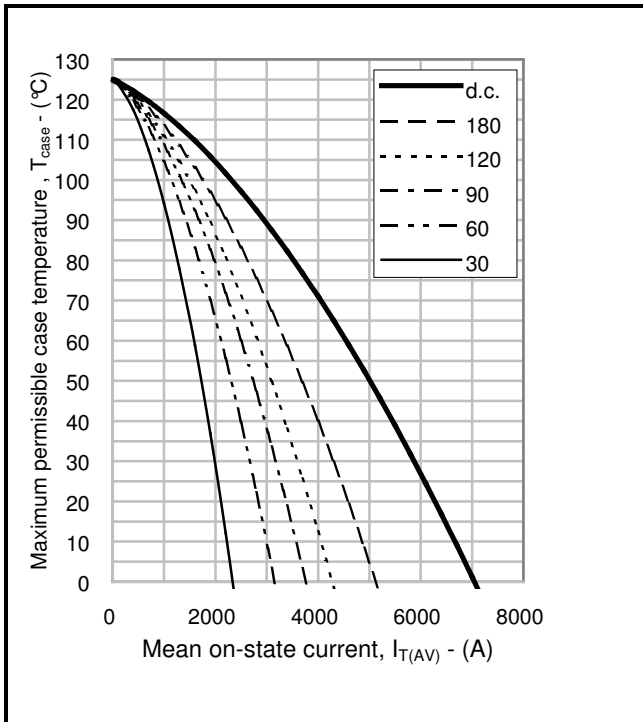


Fig.7 Maximum permissible case temperature, double side cooled – rectangular wave

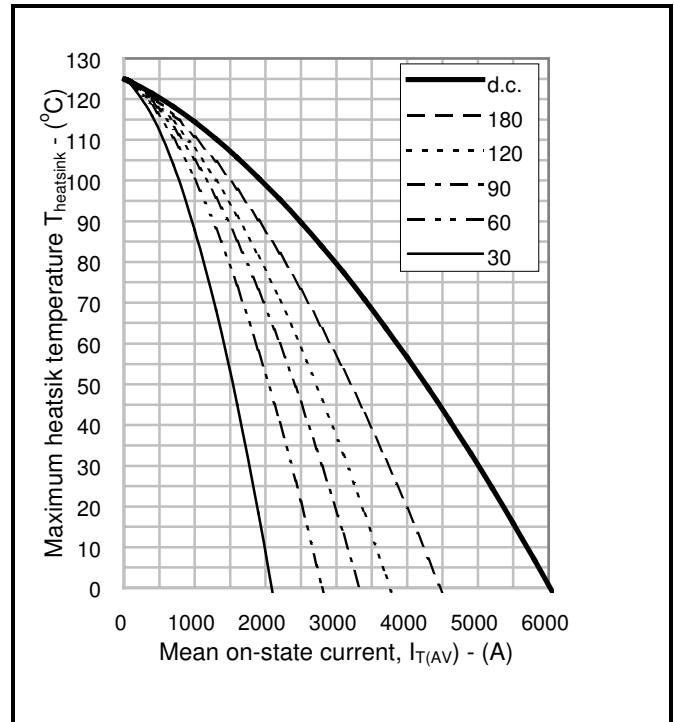


Fig.8 Maximum permissible heatsink temperature, double side cooled – rectangular wave

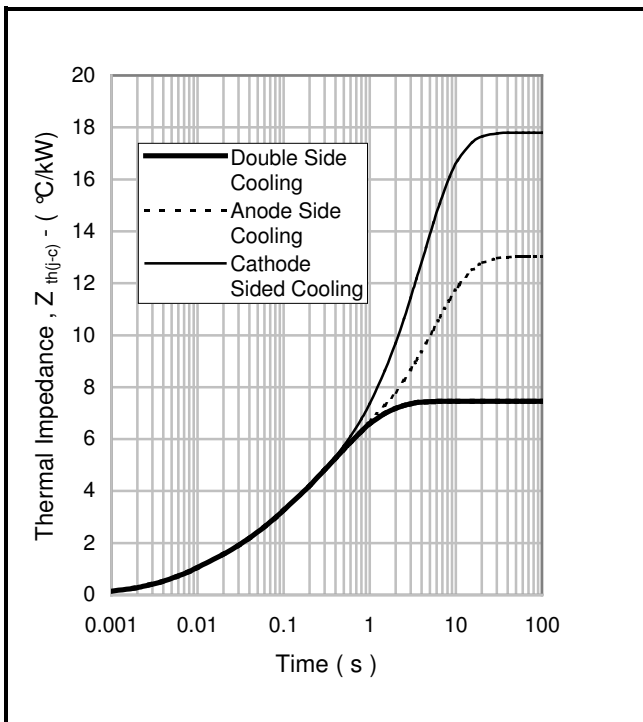


Fig.9 Maximum (limit) transient thermal impedance – junction to case (°C/kW)

		1	2	3	4
Double side cooled	R_{th} (°C/kW)	0.9206	1.8299	3.4022	1.3044
	T_1 (s)	0.0076807	0.0579454	0.4078613	1.2085
Anode side cooled	R_{th} (°C/kW)	0.9032	1.6719	3.0101	7.4269
	T_1 (s)	0.0075871	0.0536531	0.3144537	5.624
Cathode side cooled	R_{th} (°C/kW)	0.9478	2.0661	1.6884	13.0847
	T_1 (s)	0.0078442	0.0645541	0.3894389	4.1447

$$Z_{th} = \sum [R_i \times (1 - \exp. (t/t_i))] \quad [1]$$

$\Delta R_{th(j-c)}$ Conduction

Tables show the increments of thermal resistance $R_{th(j-c)}$ when the device operates at conduction angles other than d.c.

Double side cooling			Anode Side Cooling			Cathode Sided Cooling		
θ °	$\Delta Z_{th} (z)$		θ °	$\Delta Z_{th} (z)$		θ °	$\Delta Z_{th} (z)$	
	sine.	rect.		sine.	rect.		sine.	rect.
180	1.34	0.88	180	1.34	0.88	180	1.33	0.88
120	1.57	1.30	120	1.57	1.30	120	1.57	1.29
90	1.83	1.54	90	1.84	1.54	90	1.83	1.53
60	2.08	1.81	60	2.08	1.81	60	2.07	1.80
30	2.27	2.11	30	2.28	2.11	30	2.26	2.10
15	2.36	2.28	15	2.37	2.28	15	2.35	2.26

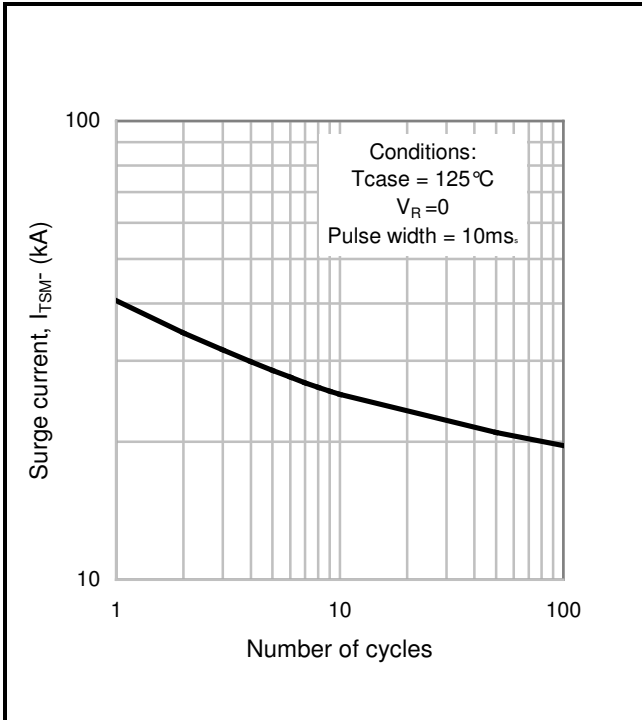


Fig.10 Multi-cycle surge current

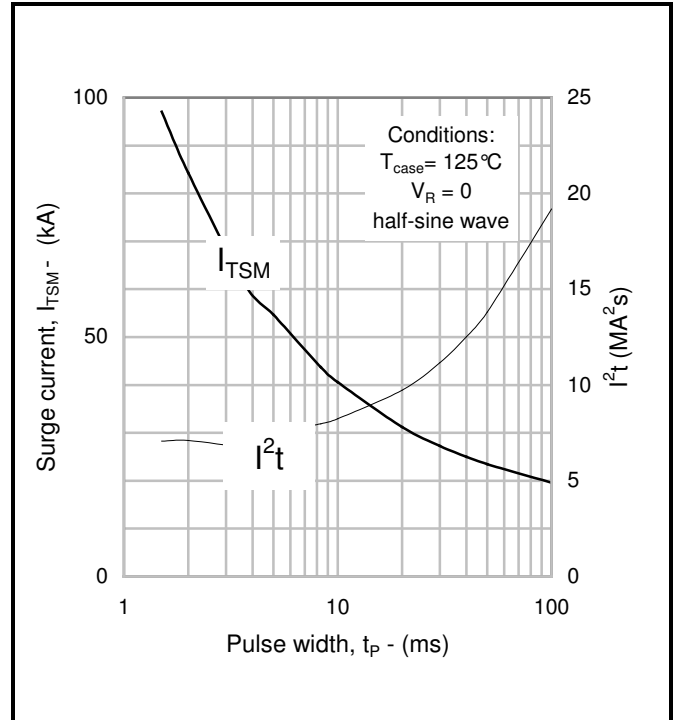


Fig.11 Single-cycle surge current

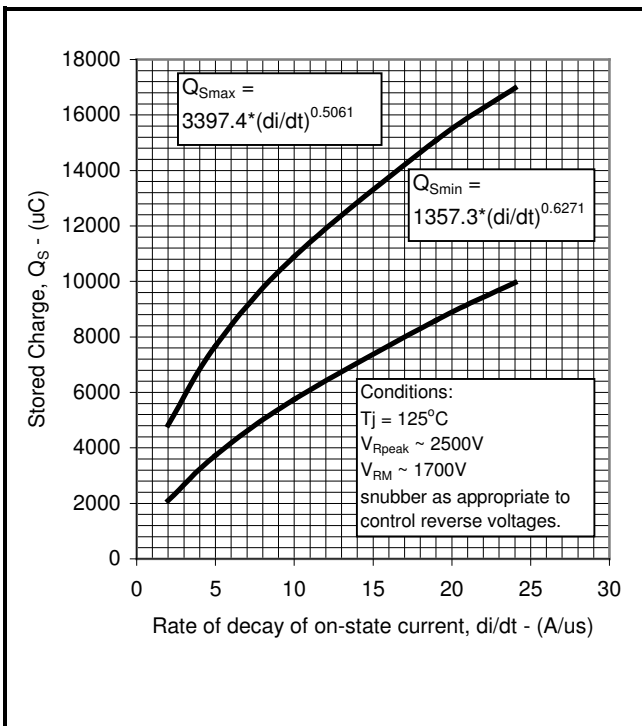


Fig. 12 Stored Charge

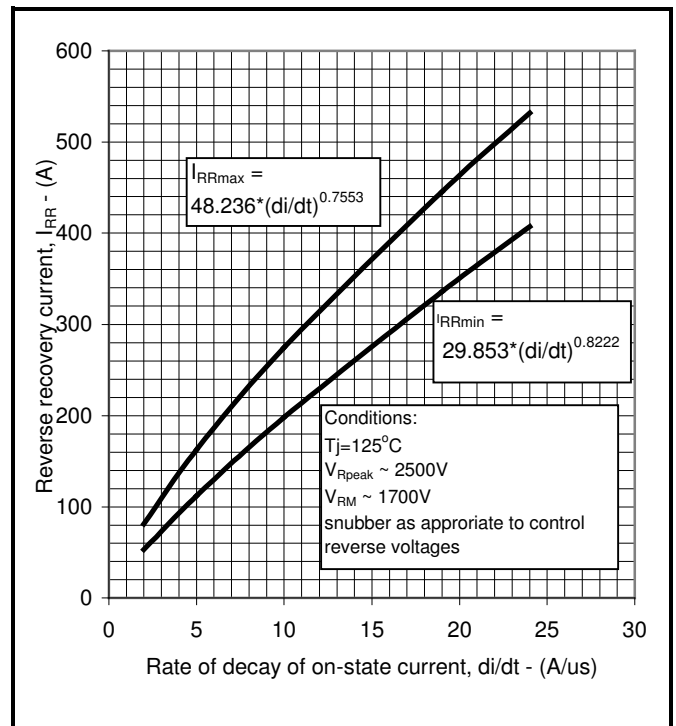


Fig. 13 Reverse Recovery Current

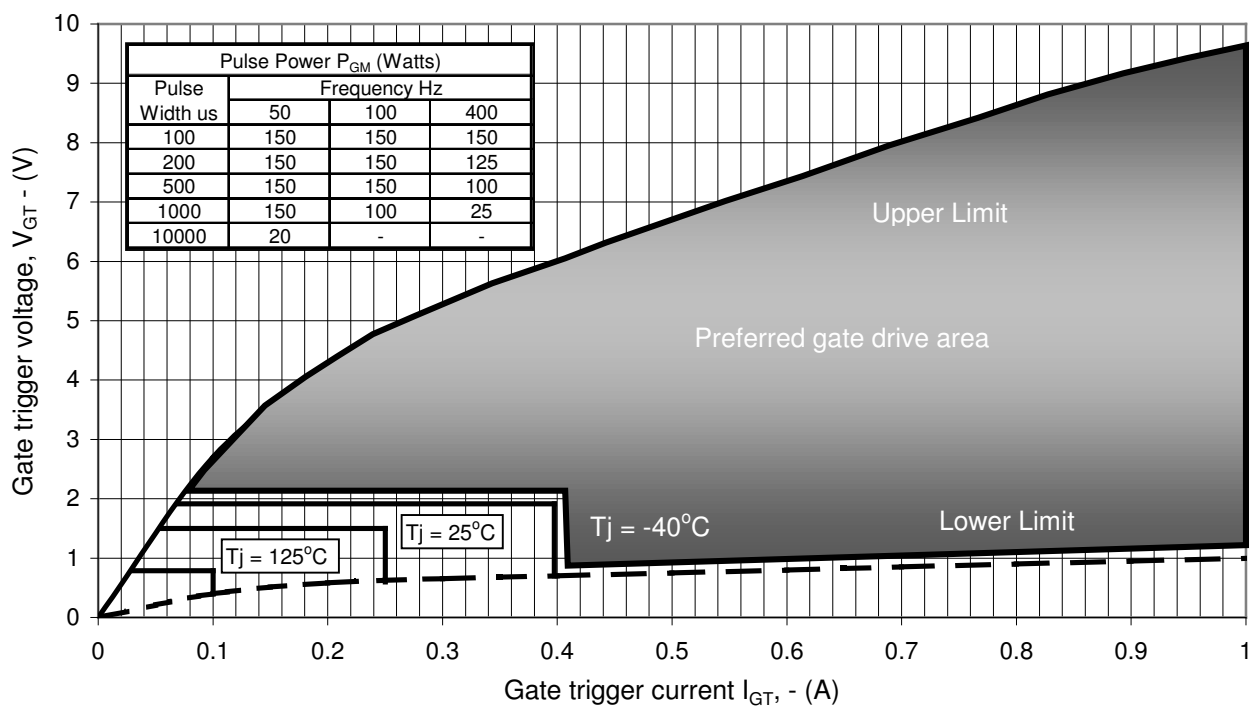


Fig14 Gate Characteristics

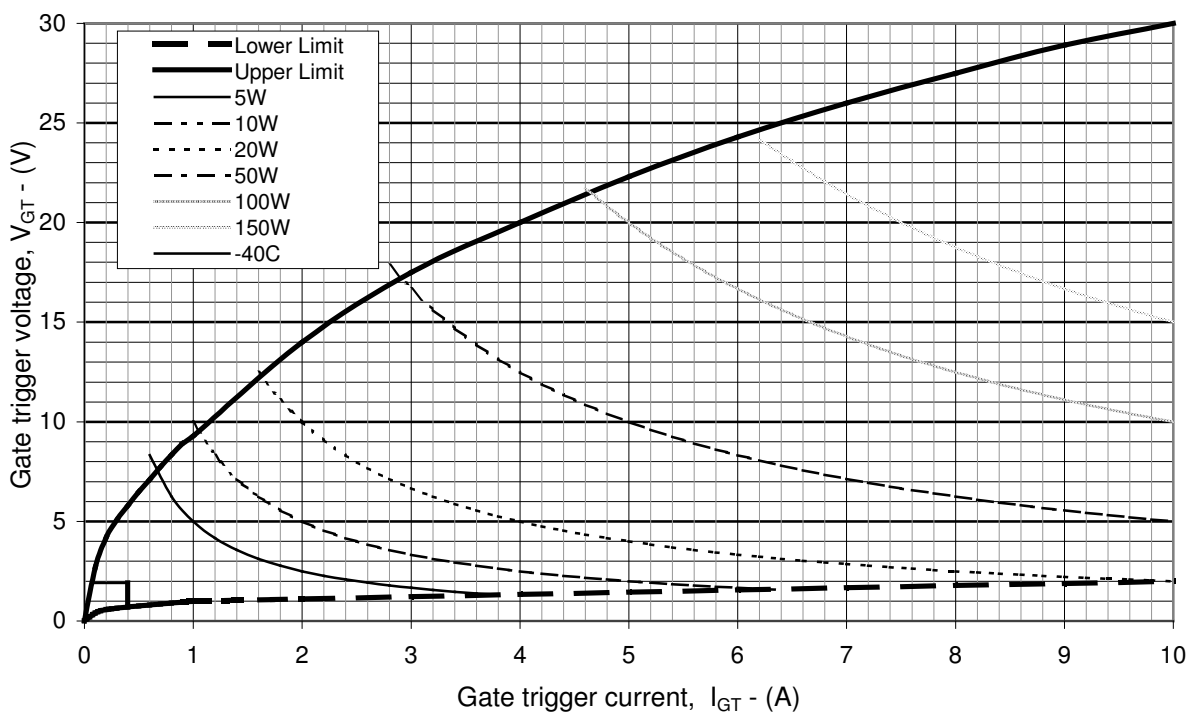
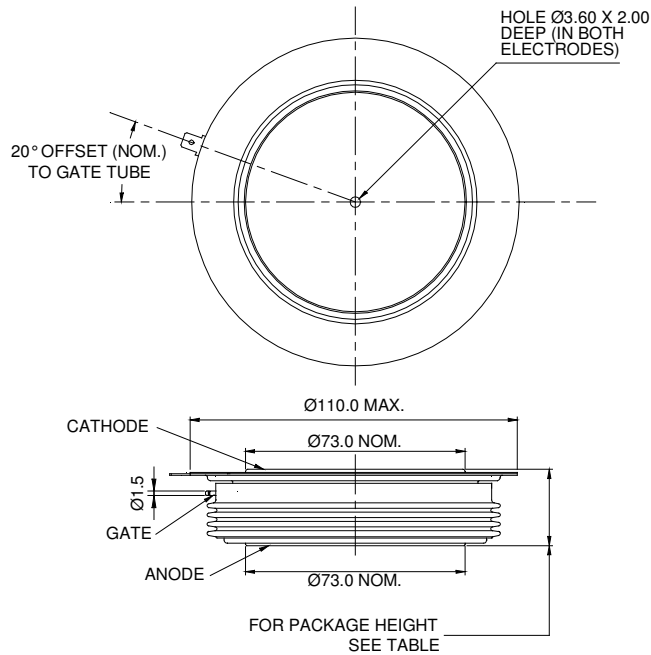


Fig. 15 Gate characteristics

PACKAGE DETAILS

For further package information, please contact Customer Services. All dimensions in mm, unless stated otherwise. DO NOT SCALE.

3rd ANGLE PROJECTION  DO NOT SCALE IF IN DOUBT ASK



Device	Maximum Thickness (mm)	Minimum Thickness (mm)
DCR1474SV18	27.265	26.515
DCR1475SV28	27.34	26.59
DCR1476SV42	27.57	26.82
DCR1478SV48	27.69	26.94
DCR1574SV28	27.34	26.59
DCR1575SV42	27.57	26.82
DCR1576SV52	27.69	26.94
DCR4060V22	27.265	26.515
DCR3780V28	27.34	26.59
DCR3030V42	27.57	26.82
DCR2720V52	27.69	26.94
DCR2290V65	27.95	27.2
DCR1910V85	28.31	27.56

Lead length: 420mm
Lead terminal connector: M4 ring

Package outline type code: V

Fig.16Package outline

POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.

Stresses above those listed in this data sheet may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed.



<http://www.dynexsemi.com>

e-mail: power_solutions@dynexsemi.com

**HEADQUARTERS OPERATIONS
DYNEX SEMICONDUCTOR LTD**
Doddington Road, Lincoln
Lincolnshire, LN6 3LF. United Kingdom.
Tel: +44(0)1522 500500
Fax: +44(0)1522 500550

CUSTOMER SERVICE
Tel: +44(0)1522 502753 / 502901. Fax: +44(0)1522 500020

© Dynex Semiconductor 2003 TECHNICAL DOCUMENTATION – NOT FOR
RESALE. PRODUCED IN UNITED KINGDOM.

This publication is issued to provide information only which (unless agreed by the Company in writing) may not be used, applied or reproduced for any purpose nor form part of any order or contract nor to be regarded as a representation relating to the products or services concerned. No warranty or guarantee express or implied is made regarding the capability, performance or suitability of any product or service. The Company reserves the right to alter without prior notice the specification, design or price of any product or service. Information concerning possible methods of use is provided as a guide only and does not constitute any guarantee that such methods of use will be satisfactory in a specific piece of equipment. It is the user's responsibility to fully determine the performance and suitability of any equipment using such information and to ensure that any publication or data used is up to date and has not been superseded. These products are not suitable for use in any medical products whose failure to perform may result in significant injury or death to the user. All products and materials are sold and services provided subject to the Company's conditions of sale, which are available on request.

All brand names and product names used in this publication are trademarks, registered trademarks or trade names of their respective owners.